



DEFENSE LOGISTICS AGENCY
DEFENSE SUPPLY CENTER, COLUMBUS
3990 E. Broad Street
COLUMBUS, OH 43213-5000

IN REPLY
REFER TO DSCC-VQC-08-016684 (Mr. Yu/614-692-0588)

November 25, 2008

SUBJECT: Laboratory Suitability Status for MIL-STD-883, FSC 5962

Keenan Evans
VP and Director, Quality & Continuous Improvement
ON Semiconductor, Inc.
2300 Buckskin Road
Pocatello, Idaho 83201

Dear Keenan:

The previous Laboratory Suitability letter VQC-06-010871 granted to ON Semiconductor (AMIS) by the Defense Supply Center, Columbus (DSCC) is superseded by this letter.

ON Semiconductor has demonstrated to the Defense Supply Center, Columbus (DSCC) compliance with MIL-STD-883, the test standard for integrated circuits. This letter is revised to reflect the current status of ON Semiconductor's Laboratory Suitability, test methods and conditions shown on the enclosure. All testing must be performed in accordance with MIL-PRF-38535 and MIL-STD-883 test methods.

This laboratory suitability is subject to the conditions in DoD 4120.24-M, Defense Standardization Program.

ON Semiconductor and QPL/QML test labs shall notify the qualifying activity immediately after learning of a potential issuance of a GIDEP alert, problem advisory or major quality/reliability problem on their QPL/QML products utilizing test methods listed on the enclosure. Failure to provide prior notification may be grounds for removal from QML-38535.

This laboratory suitability is valid until terminated by written notice from DSCC. If warranted, it may be withdrawn by DSCC at any time. Each of these facilities is subject to an audit by DSCC with a minimum notice.

Sincerely,

MICHAEL S. ADAMS
Chief
Custom Devices Branch

Enclosure

cc: ON Semiconductor (Mona Hale)
DSCC-VQC (Michael Grammens)
DSCC-VQC (Scott Thomas)

Enclosure to DSCC-VQC-08-016684

TEST	METHOD/CONDITION	ON- ID	ON- Philippines	Amkor- Technology	Hi-Rel Micro	Pantronix	Six Sigma	Kyocera	Integra Labs	Criteria Labs
Moisture Resistance	1004/None				X					
Steady State Life Test	1005/A-E		X							
Salt Atmosphere	1009/A				X					
Temperature Cycling	1010/C (1010/B for PBGA)		X	X	X			X		X
Thermal Shock	1011/B		X		X					
Seal	1014/A1,A2,C1			X	X	X		X		X
Burn-in	1015/A-F		X							
Internal Water Vapor Content	1018	Performed at Seal Laboratory, El Segundo, CA through Hi-Reliability Microelectronics								
Constant Acceleration	2001/E (Y1 Orientation)			X	X	X		X		X
Mechanical Shock	2002/B				X					
Solderability	2003/ 245C +/- 5C		X	X		X	X	X		X
Lead Integrity	2004/B2			X		X		X		X
Vibration, Variable Frequency	2007/A				X					
External Visual	2009/None	X	X	X	X	X		X		X
Internal Visual	2010/B			X		X		X		X
Bond Strength	2011/C,D	X	X	X		X		X		X
Resistance to Solvents	2015/None		X	X		X		X		X
Physical Dimensions	2016/None		X		X					
SEM	2018/Destructive	X								
Die Shear Strength	2019/None			X	X	X		X		X
PIND	2020/A							X		
Glassivation Layer Integrity	2021/A	X								
Adhesion of Lead Finish	2025/None			X		X	X			X
Substrate Attach Strength	2027/None	X		X		X		X		X
Soldering heat	2036/A,B		X	X		X	X	X		X
ESD Classification	3015/None								X	
Electrical Test	MIL-STD-883 paragraph 4.5	X	X							